

2PA1774

PNP general-purpose transistor

Rev. 04 — 24 November 2004

Product data sheet



1. Product profile

1.1 General description

PNP transistor in a SOT416 (SC-75) plastic package. The NPN complement is 2PC4617.

1.2 Features

- Low current (max. 150 mA)
- Low voltage (max. 50 V).

1.3 Applications

General-purpose switching and amplification in communication, Electronic Data Processing (EDP) and consumer applications.

2. Pinning information

Table 1: Pinning

Pin	Description	Simplified outline Symbol
1	base	
2	emitter	3
3	collector	1 1 2
		sym013

3. Ordering information

Table 2: Ordering information

Type number	Package	Package				
	Name	Description	Version			
2PA1774Q	SC-75	plastic surface mounted package; 3 leads	SOT416			
2PA1774R						
2PA1774S						



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4. Marking

Table 3: Marking codes

Type number	Marking code
2PA1774Q	YQ
2PA1774R	YR
2PA1774S	YS

5. Limiting values

Table 4: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	-60	V
V_{CEO}	collector-emitter voltage	open base	-	-50	V
V_{EBO}	emitter-base voltage	open collector	-	-6	V
I _C	collector current (DC)		-	-150	mA
I _{CM}	peak collector current		-	-200	mA
I _{BM}	peak base current		-	-100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	<u>[1]</u> _	150	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	ambient temperature		-65	+150	°C

^[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 5: Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient		<u>[1]</u> -	-	833	K/W

^[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 6: Characteristics

 T_{amb} = 25 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I _{CBO}	collector-base cut-off current	$I_E = 0 \text{ A}; V_{CB} = -30 \text{ V}$	-	-	-100	nA
		$I_E = 0 \text{ A}; V_{CB} = -30 \text{ V};$ $T_j = 150 \text{ °C}$	-	-	-5	μΑ
I _{EBO}	emitter-base cut-off current	$I_C = 0 A; V_{EB} = -4 V$	-	-	-100	nA
h _{FE}	DC current gain	$I_C = -1 \text{ mA}; V_{CE} = -6 \text{ V}$	<u>[1]</u>			
	2PA1774Q		120	-	270	
	2PA1774R		180	-	390	
	2PA1774S		270	-	560	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -50 \text{ mA};$ $I_B = -5 \text{ mA}$	[1] -	-	-200	mV
C _c	collector capacitance	$I_E = i_e = 0 \text{ A};$ $V_{CB} = -12 \text{ V}; f = 1 \text{ MHz}$	-	-	2.2	pF
f _T	transition frequency	$I_E = -2 \text{ mA};$ $V_{CE} = -12 \text{ V};$ f = 100 MHz	[1] 100	-	-	MHz

^[1] Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

8. Package outline

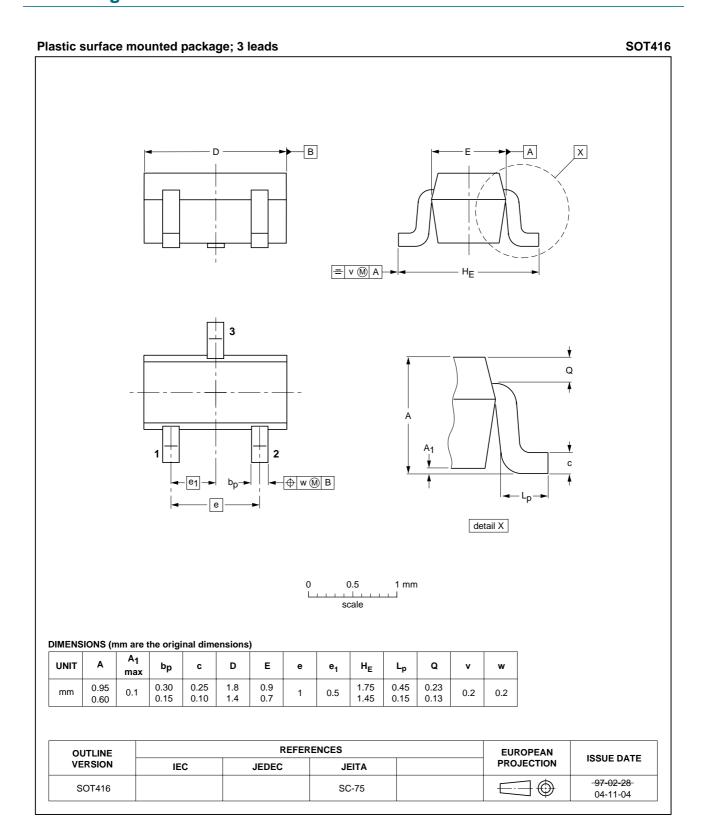


Fig 1. Package outline SOT416 (SC-75)

9397 750 14083

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Table 7: Revision history

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Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
2PA1774_4	20041124	Product data sheet	-	9397 750 14083	2PA1774_3
Modifications:		t of this data sheet has been standard of Philips Semic	9	comply with the new	v presentation and
	 Section 1.2 	2: maximum low current ar	nd maximum low v	oltage upgraded	
	• <u>Table 4</u> : V ₀	_{CBO} value changed to -60	V		
	• <u>Table 4</u> : V ₀	_{CEO} value changed to -50	V		
	• <u>Table 4</u> : V _E	_{EBO} value changed to –6 V			
	• <u>Table 4</u> : I _C	value changed to -150 m/	۹.		
2PA1774_3	20001212	Product specification	-	9397 750 07835	2PA1774_2
2PA1774_2	19990601	Preliminary specification	-	9397 750 05957	2PA1774_1
2PA1774_1	19970709	Preliminary specification	-	9397 750 02196	-

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